



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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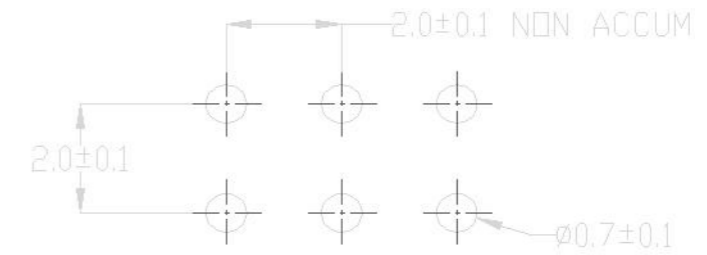
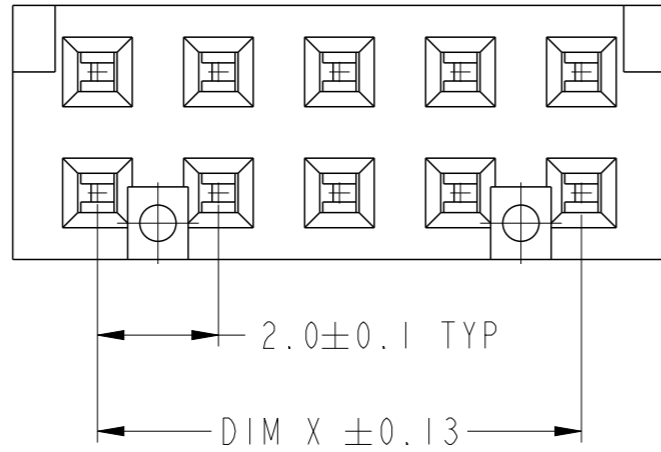


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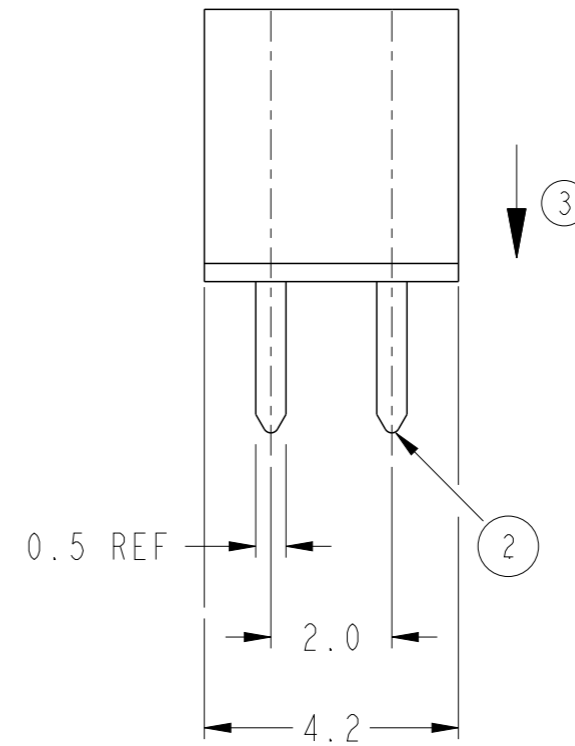
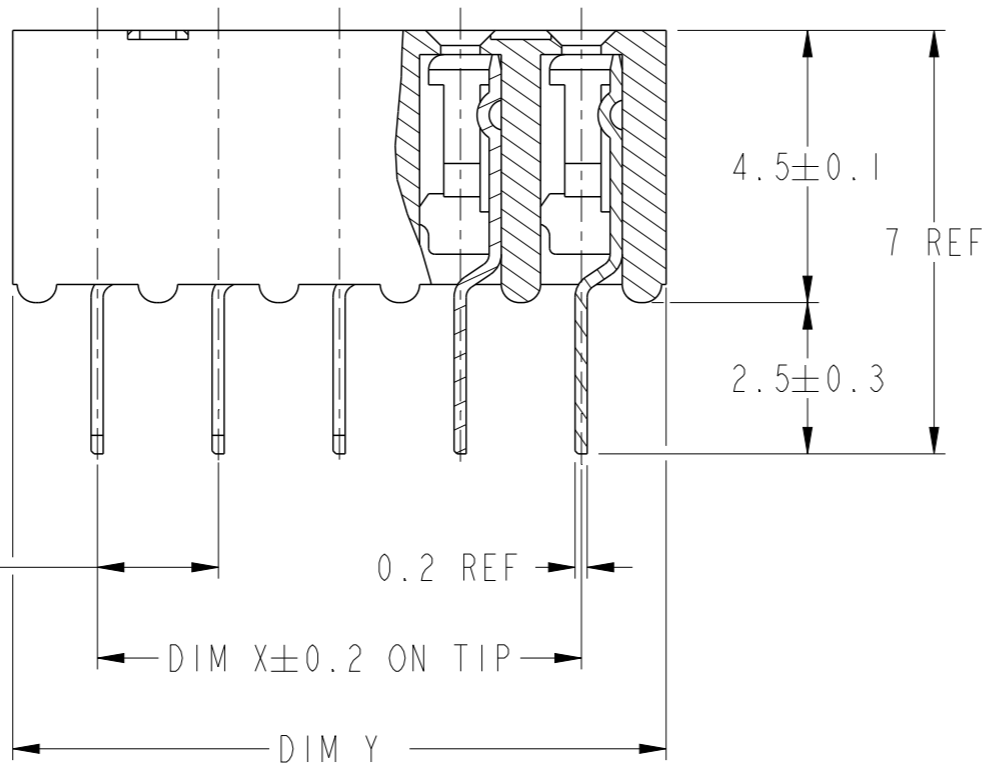
2

3

4



PC BOARD THK:0.9 TO 1.3  
RECOMMENDED MOUNTING HOLE LAYOUT



2.00±0.15 ON TIP TYP

0.2 REF

DIM X ±0.2 ON TIP

DIM Y

4.5±0.1

7 REF

2.5±0.3

0.5 REF

2.0

4.2

3

2

spec ref	*	dr	Andrew Yong	2010/10/21	projection	MM	size	A3	scale	5:1	
tolerance std	ISO 406 ISO 1101	eng	Roger Ng	2014/04/07			ecn no	ELX-N-17143-1			
surface	ISO 1302	chr	-	-			rel level	Released			
linear	0.X ±-	appr	Rick Bian	2014/04/17	product family		dwg no	63453		rev	H
angular	0° ±°	www.fci.com		cat. no.	Product - Customer Drw		sheet 1 of 2				
				<b>MINITEK II</b> VCC (HTP)							

2

3

PDS: Rev :H

STATUS:Released

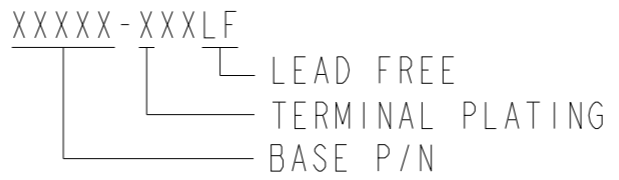
Printed: Apr 17, 2014



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PRODUCT NO	PRODUCT NO	POS	DIM X	DIM Y
63453-X04	63453-X04LF (8)	2X2	2	4.8
X06	X06LF ↑	2X3	4	6.8
X08	X08LF	2X4	6	8.8
X10	X10LF	2X5	8	10.8
X12	X12LF	2X6	10	12.8
X14	X14LF	2X7	12	14.8
X16	X16LF	2X8	14	16.8
X18	X18LF	2X9	16	18.8
X20	X20LF	2X10	18	20.8
X22	X22LF	2X11	20	22.8
X24	X24LF	2X12	22	24.8
X26	X26LF	2X13	24	26.8
X28	X28LF	2X14	26	28.8
X30	X30LF	2X15	28	30.8
X32	X32LF	2X16	30	32.8
X34	X34LF	2X17	32	34.8
X36	X36LF	2X18	34	36.8
X38	X38LF	2X19	36	38.8
X40	X40LF	2X20	38	40.8
X42	X42LF	2X21	40	42.8
X44	X44LF	2X22	42	44.8
X46	X46LF	2X23	44	46.8
X48	X48LF ↓	2X24	46	48.8
X50	X50LF (8)	2X25	48	50.8

PART NUMBER INFORMATION



NOTES:

- MATERIAL :  
 BODY : GLASS FILLED PCT UL 94V-0 BLACK  
 TERMINAL : PHOSPHOR BRONZE
- CUT SURFACE IS UNPLATED
- TERMINAL RETENTION FORCE 0.5 Kg MIN
- TOLERANCE UNLESS OTHERWISE NOTED ±0.25
- 63453-XXX PACKAGING IN TUBE WITHOUT PLASTIC CAP.  
 63453-XXXTR PACKAGING IN TAPE AND REEL WITH PLASTIC CAP.  
 63453-XXXTRN PACKAGING IN TAPE AND REEL WITHOUT PLASTIC CAP.  
 A PICK-UP CAP IS PROVIDED IN THE CENTRE OF THE PRODUCT (SEE FIG.1) FOR PICK AND PLACE APPLICATION.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255° C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

PLATING	DESCRIPTION (CONTACT AREA)
0	0.2 μm Au
1	0.76 μm Au
2	UNASSIGNED
3	0.38 μm Au
4	2.54 μm Matte Tin



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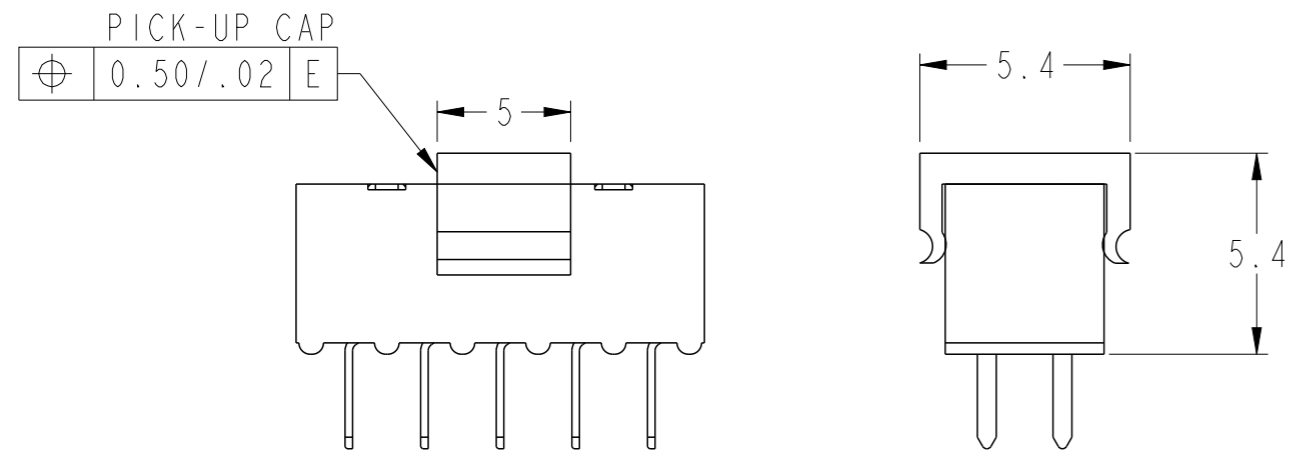


FIG 1

dr	Andrew Yong	2010/10/21	projection	MM	size	A3	scale	13:1
eng	Roger Ng	2014/04/07			ecn no		ELX-N-17143-1	
chr	-	-			rel level		Released	
appr	Rick Bian	2014/04/17	product family		-		-	
			title MINITEK II VCC (HTP)		dwg no 63453		rev H	
www.fci.com			cat. no.		-		Product - Customer Drw	
			-		-		sheet 2 of 2	